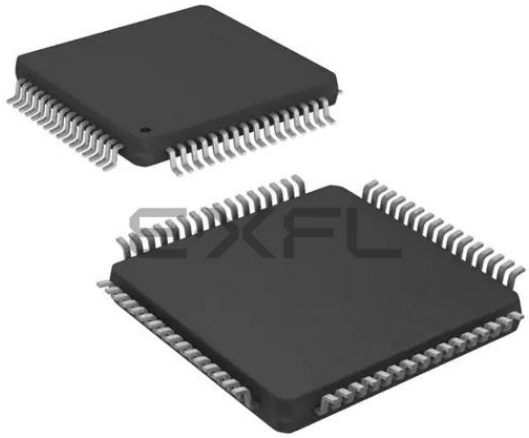


Welcome to E-XFL.COM

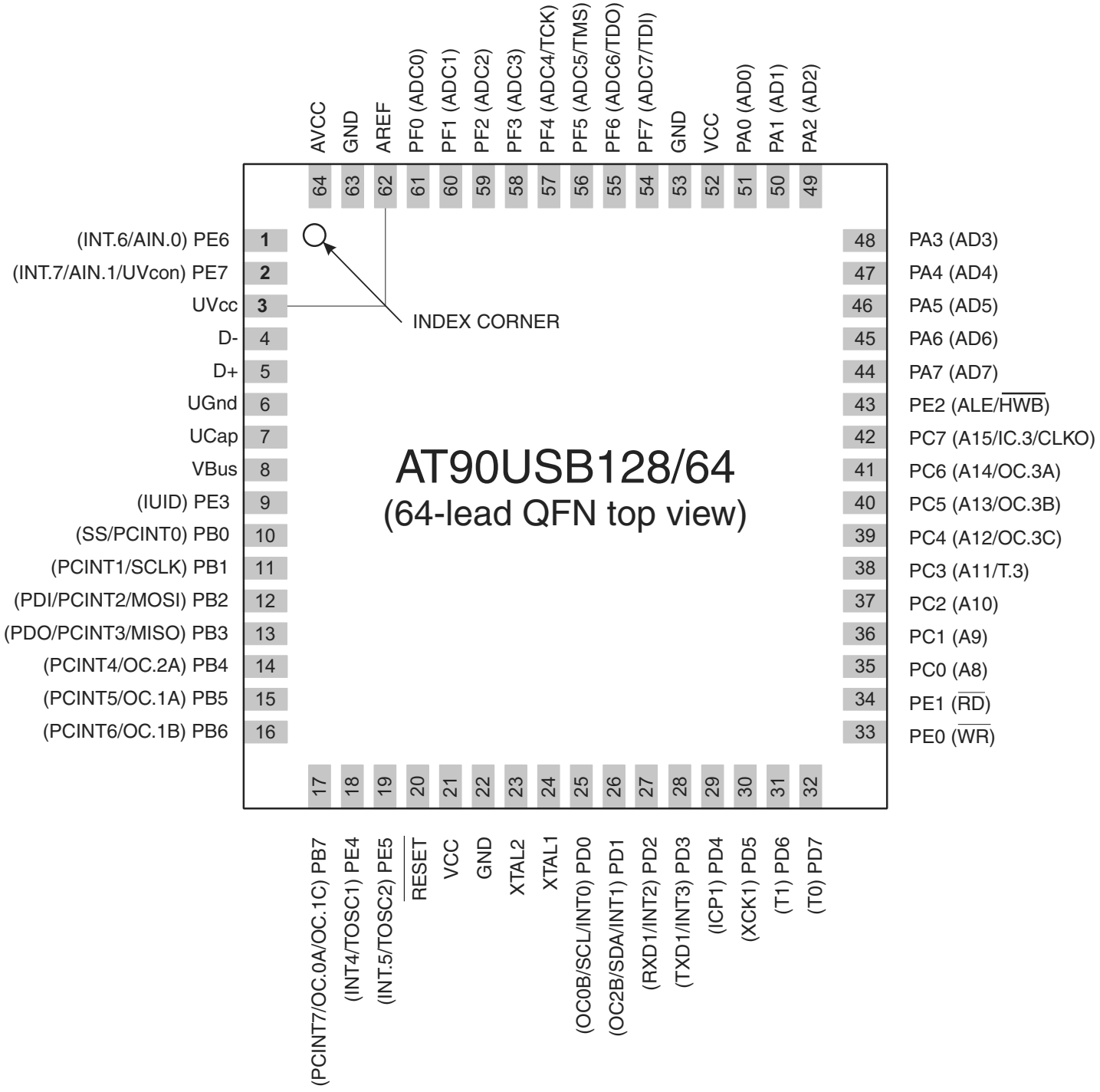
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at90usb647-au

Figure 1-2. Pinout Atmel AT90USB64/128-QFN.



Note: The large center pad underneath the MLF packages is made of metal and internally connected to GND. It should be soldered or glued to the board to ensure good mechanical stability. If the center pad is left unconnected, the package might loosen from the board.

2. Overview

The Atmel® AVR® AT90USB64/128 is a low-power CMOS 8-bit microcontroller based on the Atmel® AVR® enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the AT90USB64/128 achieves throughputs approaching 1MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The Atmel AT90USB64/128 provides the following features: 64/128Kbytes of In-System Programmable Flash with Read-While-Write capabilities, 2K/4Kbytes EEPROM, 4K/8K bytes SRAM, 48 general purpose I/O lines, 32 general purpose working registers, Real Time Counter (RTC), four flexible Timer/Counters with compare modes and PWM, one USART, a byte oriented 2-wire Serial Interface, a 8-channels, 10-bit ADC with optional differential input stage with programmable gain, programmable Watchdog Timer with Internal Oscillator, an SPI serial port, IEEE std. 1149.1 compliant JTAG test interface, also used for accessing the On-chip Debug system and programming and six software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or Hardware Reset. In Power-save mode, the asynchronous timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the Crystal/Resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

The device is manufactured using the Atmel high-density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the AT90USB64/128 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The AT90USB64/128 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

2.2 Pin descriptions

2.2.1 VCC

Digital supply voltage.

2.2.2 GND

Ground.

2.2.3 AVCC

Analog supply voltage.

2.2.4 Port A (PA7..PA0)

Port A is an 8-bit bidirectional I/O port with internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port A pins that are externally pulled low will source current if the pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port A also serves the functions of various special features of the Atmel AT90USB64/128 as listed on page 78.

2.2.5 Port B (PB7..PB0)

Port B is an 8-bit bidirectional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B has better driving capabilities than the other ports.

Port B also serves the functions of various special features of the AT90USB64/128 as listed on page 79.

2.2.6 Port C (PC7..PC0)

Port C is an 8-bit bidirectional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port C also serves the functions of special features of the AT90USB64/128 as listed on page 82.

2.2.7 Port D (PD7..PD0)

Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the AT90USB64/128 as listed on page 83.

2.2.8 Port E (PE7..PE0)

Port E is an 8-bit bidirectional I/O port with internal pull-up resistors (selected for each bit). The Port E output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port E pins that are externally pulled low will source current if the pull-up resistors are activated. The Port E pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port E also serves the functions of various special features of the AT90USB64/128 as listed on page 86.

2.2.9 Port F (PF7..PF0)

Port F serves as analog inputs to the A/D Converter.

Port F also serves as an 8-bit bidirectional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port F output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port F pins that are externally pulled low will source current if the pull-up resistors are activated. The Port F pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PF7(TDI), PF5(TMS), and PF4(TCK) will be activated even if a reset occurs.

Port F also serves the functions of the JTAG interface.

2.2.10 D-

USB Full speed / Low Speed Negative Data Upstream Port. Should be connected to the USB D- connector pin with a serial 22Ω resistor.

2.2.11 D+

USB Full speed / Low Speed Positive Data Upstream Port. Should be connected to the USB D+ connector pin with a serial 22Ω resistor.

2.2.12 UGND

USB Pads Ground.

2.2.13 UVCC

USB Pads Internal Regulator Input supply voltage.

2.2.14 UCAP

USB Pads Internal Regulator Output supply voltage. Should be connected to an external capacitor (1µF).

2.2.15 VBUS

USB VBUS monitor and OTG negociations.

2.2.16 $\overline{\text{RESET}}$

Reset input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in Table 9-1 on page 58. Shorter pulses are not guaranteed to generate a reset.

2.2.17 XTAL1

Input to the inverting Oscillator amplifier and input to the internal clock operating circuit.

2.2.18 XTAL2

Output from the inverting oscillator amplifier.

2.2.19 AVCC

AVCC is the supply voltage pin for Port F and the A/D Converter. It should be externally connected to V_{CC}, even if the ADC is not used. If the ADC is used, it should be connected to V_{CC} through a low-pass filter.

2.2.20 AREF

This is the analog reference pin for the A/D Converter.

3. Resources

A comprehensive set of development tools, application notes and datasheets are available for download on http://www.atmel.com/avr.

4. About code examples

This documentation contains simple code examples that briefly show how to use various parts of the device. Be aware that not all C compiler vendors include bit definitions in the header files and interrupt handling in C is compiler dependent. Please confirm with the C compiler documentation for more details.

These code examples assume that the part specific header file is included before compilation. For I/O registers located in extended I/O map, "IN", "OUT", "SBIS", "SBIC", "CBI", and "SBI" instructions must be replaced with instructions that allow access to extended I/O. Typically "LDS" and "STS" combined with "SBRS", "SBRC", "SBR", and "CBR".

Mnemonics	Operands	Description	Operation	Flags	#Clocks
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC ← PC + k + 1	None	1/2
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC ← PC + k + 1	None	1/2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC ← PC + k + 1	None	1/2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P,b	Set Bit in I/O Register	I/O(P,b) ← 1	None	2
CBI	P,b	Clear Bit in I/O Register	I/O(P,b) ← 0	None	2
LSL	Rd	Logical Shift Left	Rd(n+1) ← Rd(n), Rd(0) ← 0	Z,C,N,V	1
LSR	Rd	Logical Shift Right	Rd(n) ← Rd(n+1), Rd(7) ← 0	Z,C,N,V	1
ROL	Rd	Rotate Left Through Carry	Rd(0)←C,Rd(n+1)← Rd(n),C←Rd(7)	Z,C,N,V	1
ROR	Rd	Rotate Right Through Carry	Rd(7)←C,Rd(n)← Rd(n+1),C←Rd(0)	Z,C,N,V	1
ASR	Rd	Arithmetic Shift Right	Rd(n) ← Rd(n+1), n=0..6	Z,C,N,V	1
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd,Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q,Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q,Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
ELPM		Extended Load Program Memory	R0 ← (RAMPZ:Z)	None	3
ELPM	Rd, Z	Extended Load Program Memory	Rd ← (Z)	None	3
ELPM	Rd, Z+	Extended Load Program Memory	Rd ← (RAMPZ:Z), RAMPZ:Z ←RAMPZ:Z+1	None	3

Mnemonics	Operands	Description	Operation	Flags	#Clocks
SPM		Store Program Memory	(Z) ← R1:R0	None	-
IN	Rd, P	In Port	Rd ← P	None	1
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

7. Ordering information

7.1 Atmel AT90USB646

Speed [MHz]	Power supply [V]	Ordering code (2)	USB interface	Package (1)	Operating range
16 (3)	2.7-5.5	AT90USB646-AU AT90USB646-MU	Device	MD PS	Industrial (-40° to +85°C)

Notes:
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. Pb-free packaging complies to the European directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully green.
3. See “Maximum speed vs. VCC” on page 392.

MD	64 - lead, 14 × 14mm body size, 1.0mm body thickness 0.8mm lead pitch, thin profile plastic quad flat package (TQFP)
PS	64 - lead, 9 × 9mm body size, 0.50mm pitch Quad flat no lead package (QFN)

7.2 Atmel AT90USB647

Speed [MHz]	Power supply [V]	Ordering code (2)	USB interface	Package (1)	Operating range
16 (3)	2.7-5.5	AT90USB647-AU AT90USB647-MU	USB OTG	MD PS	Industrial (-40° to +85°C)

Notes:
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. Pb-free packaging complies to the European directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully green.
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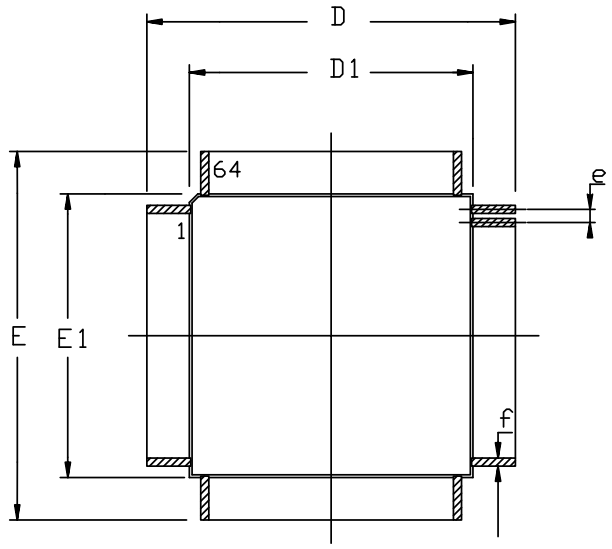
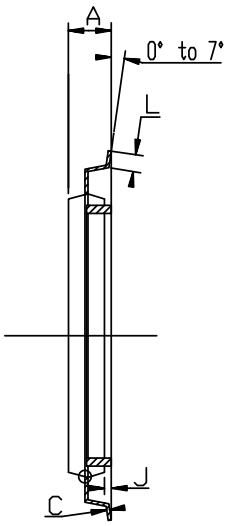
MD	64 - lead, 14 × 14mm body size, 1.0mm body thickness 0.8mm lead pitch, thin profile plastic quad flat package (TQFP)
PS	64 - lead, 9 × 9mm body size, 0.50mm pitch Quad flat no lead package (QFN)

8. Packaging information

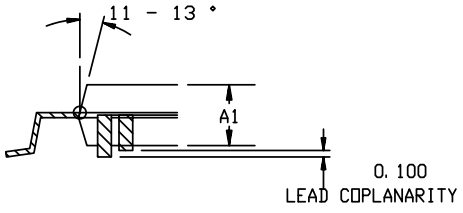
8.1 TQFP64





COMMON DIMENSIONS IN MM

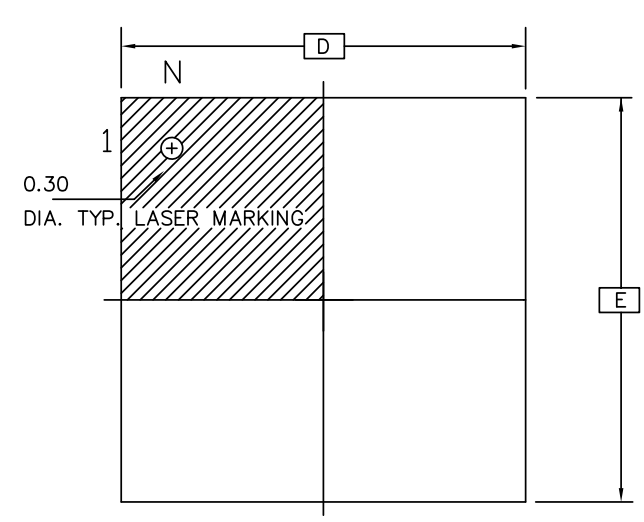
SYMBOL	Min	Max	NOTES
A	----	1.20	
A1	0.95	1.05	
C	0.09	0.20	
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
J	0.05	0.15	
L	0.45	0.75	
e	0.80 BSC		
f	0.30	0.45	

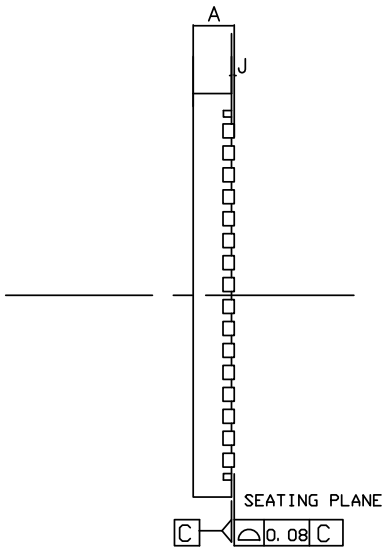


07/26/07

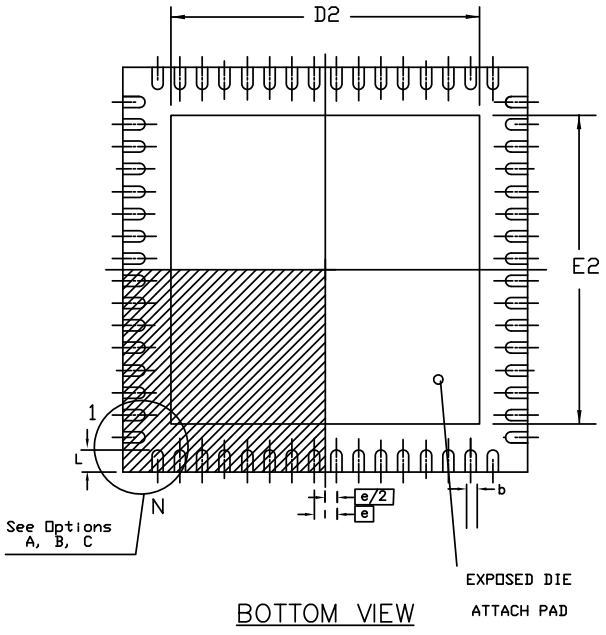
Atmel Nantes S.A. La Chantrerie - BP 70602 44306 Nantes Cedex 3 - France	TITLE MD, 64 - Lead, 14x14 mm Body Size, 1.0 mm Body Thickness 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	DRAWING No. MD	REV. F

8.2 QFN64



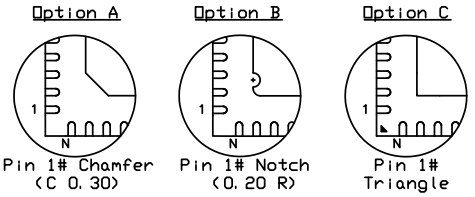


DRAWINGS NOT SCALED



COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	----	1.00	
J	0.00	----	0.05	
D/E		9.00 BSC		
D2/E2	7.40	7.50	7.60	
N		64		
e		0.50 BSC		
L	0.30	0.40	0.55	
b	0.18	0.25	0.30	



Compliant JEDEC Standard MO-220 variation VMMD-3

28/11/08

Atmel Nantes S.A. La Chantrerie - BP 70602 44306 Nantes Cedex 3 - France	TITLE PS, 64 - Lead 9.0x9.0 mm Body, 0.50 mm Pitch Quad Flat No Lead Package (QFN)	DRAWING No. PS	REV. K

9. Errata

9.1 Atmel AT90USB1287/6 errata

9.1.1 AT90USB1287/6 errata history

Silicon Release	90USB1286-16MU	90USB1287-16AU	90USB1287-16MU
First Release	Date Code up to 0648	Date Code up to 0714 and lots 0735 6H2726 (1)	Date Code up to 0701
Second Release	Date Code from 0709 to 0801 except lots 0801 7H5103 (1)	from Date Code 0722 to 0806 except lots 0735 6H2726 (1)	Date Code from 0714 to 0810 except lots 0748 7H5103 (1)
Third Release	Lots 0801 7H5103 (1) and Date Code from 0814	Date Code from 0814	Lots 0748 7H5103 (1) and Date Code from 0814
Fourth Release	TBD	TBD	TBD

Notes: 1. A blank or any alphanumeric string.

9.1.2 AT90USB1287/6 first release

- Incorrect CPU behavior for VBUSTI and IDTI interrupts routines
- USB Eye Diagram violation in low-speed mode
- Transient perturbation in USB suspend mode generates over consumption
- VBUS Session valid threshold voltage
- USB signal rate
- VBUS residual level
- Spike on TWI pins when TWI is enabled
- High current consumption in sleep mode
- Async timer interrupt wake up from sleep generate multiple interrupts

9. Incorrect CPU behavior for VBUSTI and IDTI interrupts routines

The CPU core may incorrectly execute the interrupt vector related to the VBUSTI and IDTI interrupt flags.

Problem fix/workaround

Do not enable these interrupts, firmware must process these USB events by polling VBUSTI and IDTI flags.

8. USB Eye Diagram violation in low-speed mode

The low to high transition of D- violates the USB eye diagram specification when transmitting with low-speed signaling.

Problem fix/workaround

None.

7. Transient perturbation in USB suspend mode generates overconsumption

In device mode and when the USB is suspended, transient perturbation received on the USB lines generates a wake up state. However the idle state following the perturbation does

1. **Asynchronous timer interrupt wake up from sleep generates multiple interrupts**
   If the CPU core is in sleep and wakes-up from an asynchronous timer interrupt and then go back in sleep again it may wake up multiple times.

   Problem fix/workaround
   A software workaround is to wait with performing the sleep instruction until TCNT2>OCR2+1.

9.1.3 Atmel AT90USB1287/6 second release

- Incorrect CPU behavior for VBUSTI and IDTI interrupts routines
- USB Eye Diagram violation in low-speed mode
- Transient perturbation in USB suspend mode generates over consumption
- VBUS Session valid threshold voltage
- Spike on TWI pins when TWI is enabled
- High current consumption in sleep mode
- Async timer interrupt wake up from sleep generate multiple interrupts

7. Incorrect CPU behavior for VBUSTI and IDTI interrupts routines

The CPU core may incorrectly execute the interrupt vector related to the VBUSTI and IDTI interrupt flags.

Problem fix/workaround

Do not enable these interrupts, firmware must process these USB events by polling VBUSTI and IDTI flags.

6. USB Eye Diagram violation in low-speed mode

The low to high transition of D- violates the USB eye diagram specification when transmitting with low-speed signaling.

Problem fix/workaround

None.

5. Transient perturbation in USB suspend mode generates overconsumption

In device mode and when the USB is suspended, transient perturbation received on the USB lines generates a wake up state. However the idle state following the perturbation does not set the SUSPI bit anymore. The internal USB engine remains in suspend mode but the USB differential receiver is still enabled and generates a typical 300µA extra-power consumption. Detection of the suspend state after the transient perturbation should be performed by software (instead of reading the SUSPI bit).

Problem fix/workaround

USB waiver allows bus powered devices to consume up to 2.5mA in suspend state.

4. VBUS session valid threshold voltage

The VSession valid threshold voltage is internally connected to VBus_Valid (4.4V approx.). That causes the device to attach to the bus only when Vbus is greater than VBusValid instead of V_Session Valid. Thus if VBUS is lower than 4.4V, the device is detached.

Problem fix/workaround

According to the USB power drop budget, this may require connecting the device toa root hub or a self-powered hub.

3. Spike on TWI pins when TWI is enabled

100ns negative spike occurs on SDA and SCL pins when TWI is enabled.

9.1.4 Atmel AT90USB1287/6 Third Release

- Incorrect CPU behavior for VBUSTI and IDTI interrupts routines
- Transient perturbation in USB suspend mode generates over consumption
- Spike on TWI pins when TWI is enabled
- High current consumption in sleep mode
- Async timer interrupt wake up from sleep generate multiple interrupts

5. Incorrect CPU behavior for VBUSTI and IDTI interrupts routines

The CPU core may incorrectly execute the interrupt vector related to the VBUSTI and IDTI interrupt flags.

Problem fix/workaround

Do not enable these interrupts, firmware must process these USB events by polling VBUSTI and IDTI flags.

4. Transient perturbation in USB suspend mode generates overconsumption

In device mode and when the USB is suspended, transient perturbation received on the USB lines generates a wake up state. However the idle state following the perturbation does not set the SUSPI bit. The internal USB engine remains in suspend mode but the USB differential receiver is still enabled and generates a typical 300µA extra-power consumption. Detection of the suspend state after the transient perturbation should be performed by software (instead of reading the SUSPI bit).

Problem fix/workaround

USB waiver allows bus powered devices to consume up to 2.5mA in suspend state.

3. Spike on TWI pins when TWI is enabled

100ns negative spike occurs on SDA and SCL pins when TWI is enabled.

Problem fix/workaround

No known workaround, enable AT90USB64/128 TWI first, before the others nodes of the TWI network.

2. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem fix/workaround

Before entering sleep, interrupts not used to wake up the part from sleep mode should be disabled.

1. Asynchronous timer interrupt wake up from sleep generates multiple interrupts

If the CPU core is in sleep mode and wakes-up from an asynchronous timer interrupt and then goes back into sleep mode, it may wake up multiple times.

9.1.5 Atmel AT90USB1287/6 Fourth Release

- Transient perturbation in USB suspend mode generates over consumption
- Spike on TWI pins when TWI is enabled
- High current consumption in sleep mode
- Async timer interrupt wake up from sleep generate multiple interrupts

4. **Transient perturbation in USB suspend mode generates overconsumption**
   In device mode and when the USB is suspended, transient perturbation received on the USB lines generates a wake up state. However the idle state following the perturbation does not set the SUSPI bit. The internal USB engine remains in suspend mode but the USB differential receiver is still enabled and generates a typical 300µA extra-power consumption. Detection of the suspend state after the transient perturbation should be performed by software (instead of reading the SUSPI bit).

   Problem fix/workaround
   USB waiver allows bus powered devices to consume up to 2.5mA in suspend state.

3. **Spike on TWI pins when TWI is enabled**
   100ns negative spike occurs on SDA and SCL pins when TWI is enabled.

   Problem fix/workaround
   No known workaround, enable Atmel AT90USB64/128 TWI first, before the others nodes of the TWI network.

2. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem fix/workaround
   Before entering sleep, interrupts not used to wake up the part from sleep mode should be disabled.

1. **Asynchronous timer interrupt wake up from sleep generates multiple interrupts**
   If the CPU core is in sleep mode and wakes-up from an asynchronous timer interrupt and then goes back into sleep mode, it may wake up multiple times.

   Problem fix/workaround
   A software workaround is to wait before performing the sleep instruction: until TCNT2>OCR2+1.

9.2.3 Atmel AT90USB646/7 Second Release.

- USB Eye Diagram violation in low-speed mode
- Transient perturbation in USB suspend mode generates over consumption
- Spike on TWI pins when TWI is enabled
- High current consumption in sleep mode
- Async timer interrupt wake up from sleep generate multiple interrupts

5. USB Eye Diagram violation in low-speed mode

The low to high transition of D- violates the USB eye diagram specification when transmitting with low-speed signaling.

Problem fix/workaround
None.

4. Transient perturbation in USB suspend mode generates overconsumption

In device mode and when the USB is suspended, transient perturbation received on the USB lines generates a wake up state. However the idle state following the perturbation does not set the SUSPI bit anymore. The internal USB engine remains in suspend mode but the USB differential receiver is still enabled and generates a typical 300µA extra-power consumption. Detection of the suspend state after the transient perturbation should be performed by software (instead of reading the SUSPI bit).

Problem fix/workaround
USB waiver allows bus powered devices to consume up to 2.5mA in suspend state.

3. Spike on TWI pins when TWI is enabled

100ns negative spike occurs on SDA and SCL pins when TWI is enabled.

Problem fix/workaround
No known workaround, enable Atmel AT90USB64/128 TWI first versus the others nodes of the TWI network.

2. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem fix/workaround
Before entering sleep, interrupts not used to wake up the part from the sleep mode should be disabled.

1. Asynchronous timer interrupt wake up from sleep generates multiple interrupts

If the CPU core is in sleep and wakes-up from an asynchronous timer interrupt and then go back in sleep mode again it may wake up several times.

Problem fix/workaround
A software workaround is to wait with performing the sleep instruction until TCNT2>OCR2+1.

10. Datasheet revision history for Atmel AT90USB64/128

Please note that the referring page numbers in this section are referred to this document. The referring revision in this section are referring to the document revision.

10.1 Changes from 7593A to 7593B

1. Changed default configuration for fuse bytes and security byte.
2. Suppression of timer 4,5 registers which does not exist.
3. Updated typical application schematics in USB section

10.2 Changes from 7593B to 7593C

1. Update to package drawings, MQFP64 and TQFP64.

10.3 Changes from 7593C to 7593D

1. For further product compatibility, changed USB PLL possible prescaler configurations. Only 8MHz and 16MHz crystal frequencies allows USB operation (see Table 7-11 on page 50).

10.4 Changes from 7593D to 7593E

1. Updated PLL Prescaler table: configuration words are different between AT90USB64x and AT90USB128x to enable the PLL with a 16MHz source.
2. Cleaned up some bits from USB registers, and updated information about OTG timers, remote wake-up, reset and connection timings.
3. Updated clock distribution tree diagram (USB prescaler source and configuration register).
4. Cleaned up register summary.
5. Suppressed PCINT23:8 that do not exist from External Interrupts.
6. Updated Electrical Characteristics.
7. Added Typical Characteristics.
8. Update Errata section.

10.5 Changes from 7593E to 7593F

1. Removed 'Preliminary' from document status.
2. Clarification in Stand by mode regarding USB.

10.6 Changes from 7593F to 7593G

1. Updated Errata section.

10.7 Changes from 7593G to 7593H

1. Added Signature information for 64K devices.
2. Fixed figure for typical bus powered application
3. Added min/max values for BOD levels
4. Added ATmega32U6 product
5. Update Errata section
6. Modified descriptions for HWUPE and WAKEUPE interrupts enable (these interrupts should be enabled only to wake up the CPU core from power down mode).

7. Added description to access unique serial number located in Signature Row see “Reading the Signature Row from software” on page 354.

10.8 Changes from 7593H to 7593I

1. Updated Table 9-2 in “Brown-out detection” on page 60. Unused BOD levels removed.

10.9 Changes from 7593I to 7593J

1. Updated Table 9-2 in “Brown-out detection” on page 60. BOD level 100 removed.
2. Updated “Ordering information” on page 18.
3. Removed ATmega32U6 errata section.

10.10 Changes from 7593J to 7593K

1. Corrected Figure 6-7 on page 34, Figure 6-8 on page 34 and Figure 6-9 on page 35.
2. Corrected ordering information for Section 7.3 ”Atmel AT90USB1286” on page 20, Section 7.4 ”Atmel AT90USB1287” on page 21 andSection 7.2 ”Atmel AT90USB647” on page 19.
3. Removed the ATmega32U6 device and updated the datasheet accordingly.
4. Updated Assembly Code Example in “Watchdog reset” on page 61.

10.11 Changes from 7593K to 7593L

1. Updated the “Ordering information” on page 18. Changed the speed from 20MHz to 16MHz.
2. Replaced ATmegaAT90USBxxxx by AT90USBxxxx through the datasheet.
3. Updated the first paragraph of “Overview” on page 307. Port A replaced by Port F.
4. Updated ADC equation in “ADC conversion result” on page 318. The equation has 1024 instead of 1023.
5. Created “Packaging Information” chapter.
6. Replaced the “QFN64” Packaging by an updated QFN64 Packaging drawing.
7. Updated “Errata” on page 26. AT90USB1286/7 has a fourth release, while AT90USB646/7 updated with a second release.
8. In Section “Overview” on page 307, “Port A” has been replaced by “Port F” in the first section.
9. In Section “Atmel AT90USB647” on page 19 the USB interface has been changed to USB OTG.
10. In Section “Atmel AT90USB1286” on page 20 the USB interface has been changed to Device.
11. In Section “Atmel AT90USB1287” on page 21 the USB interface has been changed to Host OTG.
12. General update according to new template.